Title (en)

METHOD FOR DRY CHEMICAL TREATMENT OF SUBSTRATES AND USE THEREOF

Title (de)

VERFAHREN ZUR TROCKENCHEMISCHEN BEHANDLUNG VON SUBSTRATEN, SOWIE DESSEN VERWENDUNG

Title (fr)

PROCEDE POUR REALISER UN TRAITEMENT CHIMIQUE A SEC DE SUBSTRATS, ET SON UTILISATION

Publication

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Application

EP 06829345 A 20061206

Priority

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Abstract (en)

[origin: WO2007065658A2] The invention relates to a method for dry chemical treatment of substrates, selected from the group comprising silicon, ceramics, glass and quartz glass, wherein the substrate is treated in a heated reaction chamber with a gas containing hydrogen chloride as etching agent and a substrate produced as above. The invention further relates to uses of said method.

IPC 8 full level

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Citation (search report)

See references of WO 2007065658A2

Citation (examination)

- JP 2003100693 A 20030404 - TOSHIBA CERAMICS CO
- EP 0617456 A2 19940928 - GI CORP [US]
- JP H11121441 A 19990430 - FUJI ELECTRIC CO LTD

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DOCDB simple family (application)

DE 102005058713 A 20051208; CN 200680045865 A 20061206; EP 06829345 A 20061206; EP 2006011716 W 20061206; JP 2008543722 A 20061206; US 9627106 A 20061206